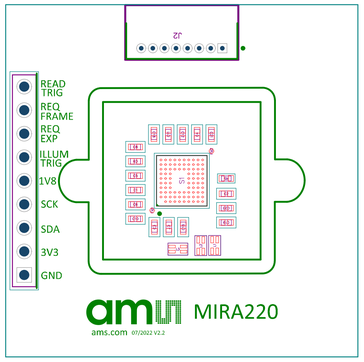
Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	SM-002	0,025mm	4	
1	Top Layer	CF-004	0,035mm		
	Dielectric 4	PP-006	0,071mm	4.1	
	Dielectric 6	PP-006	0,071mm	4.1	
2	Layer 2	CF-004	0,035mm		
	Dielectric 3	Core-039	0,711mm	4.8	
3	Layer 3	CF-004	0,035mm		
	Dielectric 7	PP-006	0,071mm	4.1	
	Dielectric 5	PP-006	0,071mm	4.1	
4	Bottom Layer	CF-004	0,035mm		
	Bottom Solder	SM-002	0,025mm	4	
	Bottom Overlay				

Total board thickness: 1,186mm



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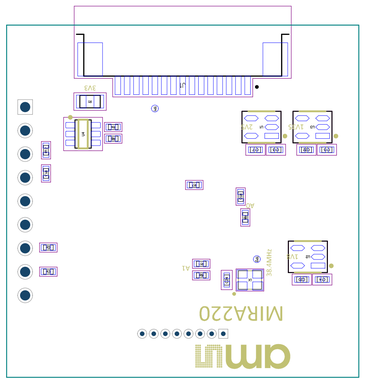
Drawn	Checked	Drawing No.
MKOC		

Title, Comments
MIRA220 CSP
Reference Design - RPI

Project
MIRA220

Rev.	Date	size	scale
2.2	**11-July-2022**	A4	1:1

mm 0 50 100



Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	SM-005	0.052mm	4	
1	Top Layer	CT-004	0.035mm		
	Dielectric 4	pp-005	0.051mm	4.1	
	Dielectric 6	pp-005	0.051mm	4.1	
2	Layer 2	CT-004	0.035mm		
	Dielectric 3	core-035	0.511mm	4.8	
	Layer 3	CT-004	0.035mm		
	Dielectric 5	pp-005	0.051mm	4.1	
	Dielectric 7	pp-005	0.051mm	4.1	
4	Bottom Layer	CT-004	0.035mm		
	Bottom Solder	SM-005	0.052mm	4	
	Bottom Overlay				

Total board thickness: 1.184mm

	Title, Comments		Project		
	MIRA220 CSP		MIRA220		
	Reference Design - RPI		Rev.	Date	Size A4
			S.S	11-July-2022	Scale 1:1
	Drawn	Checked	Drawing No.		
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